



SOT549-1

plastic thermal enhanced thin shrink small outline package;
32 leads; body width 6.1 mm; lead pitch 0.65 mm; exposed
die pad

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	HTSSOP32
Package type industry code	HTSSOP32
Package style descriptive code	HTSSOP (thermal enhanced thin shrink small outline package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MO-153
Mounting method type	S (surface mount)
Issue date	2-11-2005

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	10.9	-	11	11.1	mm
E	package width	6	-	6.1	6.2	mm
A	seated height	[tbd]	-	1.1	1.1	mm
A ₂	package height	0.85	-	0.9	0.95	mm
n ₂	actual quantity of termination	-	-	32	-	

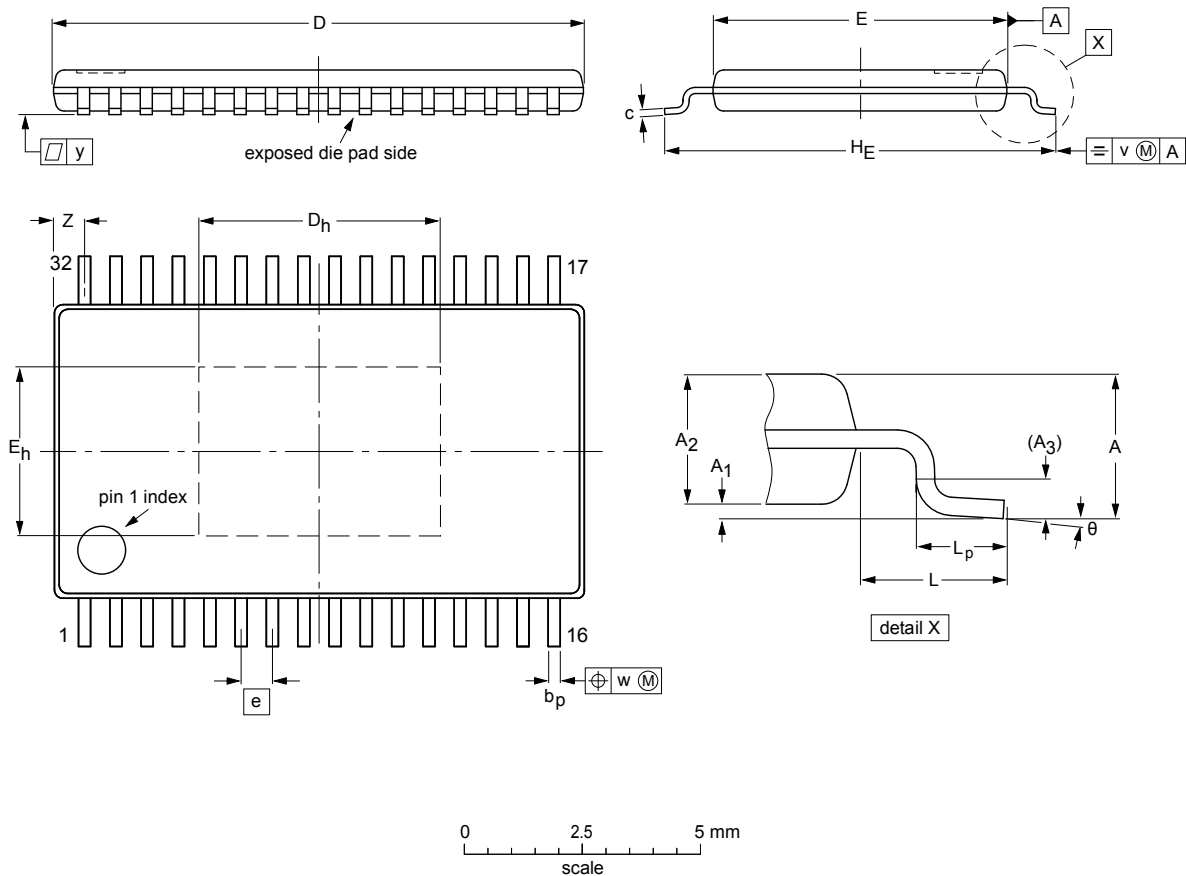


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2. Package outline

HTSSOP32: plastic thermal enhanced thin shrink small outline package; 32 leads; body width 6.1 mm; lead pitch 0.65 mm; exposed die pad

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DIMENSIONS (mm are the original dimensions).

UNIT	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	D _h	E ⁽²⁾	E _h	e	H _E	L	L _p	v	w	y	Z	θ
mm	1.1	0.15 0.05	0.95 0.85	0.25	0.30 0.19	0.20 0.09	11.1 10.9	5.1 4.9	6.2 6.0	3.6 3.4	0.65	8.3 7.9	1	0.75 0.50	0.2	0.1	0.1	0.78 0.48	8° 0°

Notes

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT549-1		MO-153				03-04-07 05-11-02

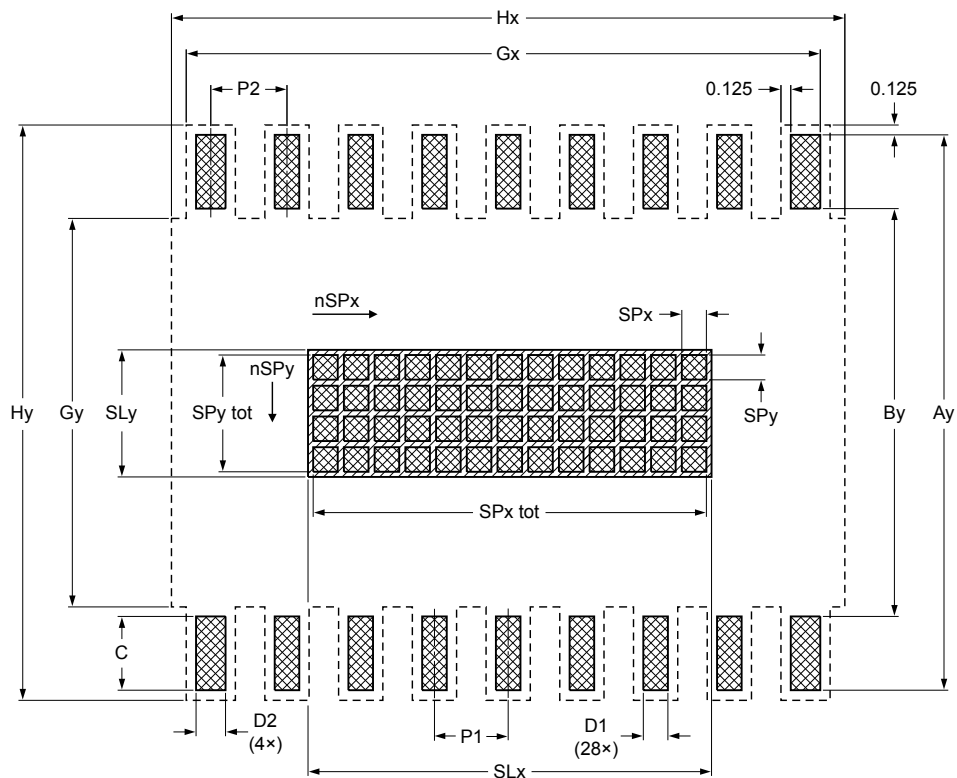
Fig. 1. Package outline HTSSOP32 (SOT549-1)

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3. Soldering

Footprint information for reflow soldering of HTSSOP32 package

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Generic footprint pattern
Refer to the package outline drawing for actual layout

- solder land
- solder land plus solder paste
- occupied area

nSPx	nSPy
4	3

DIMENSIONS in mm

P1	P2	Ay	By	C	D1	D2	SLx	SLy	SPx tot	SPy tot	SPx	SPy	Gx	Gy	Hx	Hy
0.650	0.700	8.600	6.200	1.200	0.400	0.500	5.200	3.800	5.100	3.700	1.000	0.800	10.600	6.500	11.400	8.850

Issue date 09-12-28
12-01-26

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Fig. 2. Reflow soldering footprint for HTSSOP32 (SOT549-1)

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4. Legal information

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